

Title (en)

METHOD AND DEVICE FOR EQUALIZING THE SOLIDIFICATION PROCESS OF A FUSIBLE METAL, PARTICULARLY PRODUCED BY MEANS OF STRAND OR STRIP CASTING

Title (de)

VERFAHREN UND VORRICHTUNG ZUM VERGLEICHMÄSSIGEN DES ERSTARRUNGSVORGANGES EINES INSBESONDERE BEIM STRANG- ODER BANDGIESSEN ERZEUGTEN SCHMELZFLÜSSIGEN METALLES

Title (fr)

PROCÉDÉ ET DISPOSITIF POUR UNIFORMISER LE PROCESSUS DE SOLIDIFICATION D'UN MÉTAL EN FUSION PRODUIT NOTAMMENT PAR COULÉE CONTINUE OU EN BANDE

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Abstract (en)

[origin: CA2705222A1] The invention relates to a method for equalizing the solidification process of a fusible metal (10), particularly a fusible metal produced by means of strand or strip casting, wherein the fusible metal (10) is subjected particularly to an electromagnetic stirring process, and wherein a magnetic field is applied to the metal located there upstream of the point of the particularly electromagnetic stirring process. The invention proposes that at least one electromagnetic field be applied to the regions (11) of the fusible metal 10 already solidified into a strand on the exterior. The invention further relates to a device for carrying out said method.

IPC 8 full level

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